



Material declaration form

General Information							
IPC	1752	Version	2				
Form type*	Distribute	Version	2				
Sectionals*	Material information	Subsectionals*	A-D				
	Manufacturing information	*: Required Field					

Supplier Information							
Company name*	STMicroelectronics	Response Date*	2025-07-09				
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section				
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section				
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion				
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section				
Supplier comment	Online Technical Support - STMicroelectronics http://www.st.com/web/en/support/support.htm						

Uncertainty statement

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Legal statement Supplier acceptance* true Legal declaration* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

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Product								
Mfr item number	Mfr item name	Version	Manufacturing site	date				
STM32L552RET6Q	625W*472XXXZ	A	998Z	2025-07-09				
	Amount	Unit of measure	Unit type	ST ECOPACK grade				
	359	mg	Each	ECOPACK® 2				

anufacturing information								
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles						
3	260	3						
Bulk solder termination	Terminal plating	Terminal base alloy	Comment					
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0					
Package designator	Package size	Number of instances	Shape					
QFP	10x10	64	Gull wing					
Comment	Package: 5W LQFP 64 10x10x1.4 1 0051434							

QueryList: RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015 Response						
1 - Product(s) meets EU RoHS requireme	true					
2 - Product(s) meets EU RoHS requireme apply)	false					
3 - Product(s) meets EU RoHS requireme	false					
4 - Product(s) does not meet EU RoHS re	false					
Exemption Id.	Description					
,						

QueryList : REACH-21st January 2025	Response			
	Response			
1 - Product(s) does not contain REACH S	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	ppm in product	
,	#N/A			

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Material Composition Declaration: note: Substance present with less 0.001mg_will not be declared in this document					Mfr Item Name	625W'472XXXZ		359.3701		6000000.0	1000000.0	
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration is product (ppm)
Die or dies	M-011 Other inorganic materials	15.887	mg	supplier	die	Silicon (Si)	7440-21-3		14.485	mg	911738	40306.25
				supplier	metallization	Aluminium (AI)	7429-90-5		0.064	mg	4032	178.25
				supplier	metallization	Copper (Cu)	7440-50-8		0.598	mg	37634	1663.73
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.192	mg	12097	534.79
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	448	19.81
				supplier	metallization	Tungsten (W)	7440-33-7		0.007	mg	448	19.81
				supplier	Passivation	Silicon Nitride	12033-89-5		0.149	mg	9409	415.95
				supplier	Passivation	Silicon Oxide	7631-86-9		0.384	mg	24194	1069.57
Glue epoxy (EN4900GC)	Other Organic Materials	0.912	mg	supplier	Organic Compounds	Acrylic resin	Proprietary		0.064	mg	70000	177.70
				supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.018	mg	20000	50.77
				supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.014	mg	15000	38.08
				supplier	Organic Compounds	Acrylate	Proprietary		0.049	mg	54000	137.08
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.027	mg	30000	76.16
				supplier	Organic Compounds	Peroxide	Proprietary		0.007	mg	8000	20.31
				supplier	Organic Compounds	Additive	Proprietary		0.016	mg	18000	45.69
				supplier	Metals	Silver	7440-22-4		0.716	mg	785000	1992.81
Encapsualtion (EME-G700LAL-A)	Other Organic Materials	236.000	mg	supplier	Organic Compounds	Epoxy Resin	Proprietary		12.980	mg	55000	36118.81
				supplier	Organic Compounds	Phenol Resin	Proprietary		4.956	mg	21000	13790.82
				supplier	Glass	Silica(Amorphous)A	60676-86-0		188.800	mg	800000	525364.48
				supplier	Glass	Silica(Amorphous)B	7631-86-9		28.084	mg	119000	78147.97
				supplier	Organic Compounds	Carbon Black	1333-86-4		1.180	mg	5000	3283.53
Bonding wire (Cu)	Bonding Wire	0.833	mg	supplier	Metals	Copper	7440-50-8		0.804	mg	965500	2236.64
				supplier	Metals	Palladium	7440-05-3		0.026	mg	31000	71.81
				supplier	Metals	Gold	7440-57-5		0.003	mg	3500	8.11
Plating anode (Sn)	Other inorganic materials	1.438	mg	supplier	Metals	Tin	7440-31-5		1.438	mg	1000000	4001.05
Leadframe (C7025 + Ag)	Copper & its alloys	104.300	mg	supplier	Metals	Copper	7440-50-8		101.536	mg	973499	282538.63
3,				supplier	Metals	Iron	7439-89-6		2.377	mg	22790	6614.34
				supplier	Metals	Phosphor	7723-14-0		0.026	mg	250	72.56
				supplier	Metals	Zinc	7440-66-6		0.131	mg	1260	365.69
				supplier	Metals	Siliver	7440-22-4		0.229	mg	2200	638.51
				SVHC	Metals	Lead	7439-92-1		0.000	mg	1	0.29

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